Sensors and Materials

Special Issue on Sensors, Materials, and Computational Intelligence Algorithms in Robotics and AI Engineering

Call for Papers

Robotics and artificial intelligence (RAI) engineering plays an important role in not only the industrial sector but also the commercial and environmental sectors. Industry 4.0, AI, the financial sector, and many other sectors have been developed and impacted by this engineering discipline, especially AI. Many problems in engineering and industry that cannot be solved by conventional or mathematical methods can be solved by RAI. Unquestionably, the essential parts of RAI are sensors, materials, and computational intelligence. New sensors and materials will lead to a new era of development in RAI along with industrial and commercial applications, in addition to the development of new computational intelligence, and thus lead to the next generation of applications in many sectors. With this background, this special issue focuses on the new and smart development of materials, sensors, and computational intelligence in the RAI field to solve problems in the industrial, commercial, and environmental sectors. Prospective authors are invited to submit manuscripts in line with the scope and areas of focus of this special issue.

Scope:
– Smart sensors and materials in robotics and automation
– Smart IoT for robotics and AI
– Machine learning in robotics
– Nanomaterials and their applications in RAI
– Sensor fusion, sensorless applications
– Augmented/virtual reality in RAI applications
– Automation and IoT in early warning systems for the environment
– Smart microsensors and actuators in RAI
– New algorithms in computational intelligence and AI
– Neural networks, fuzzy logic, search algorithms
– New algorithms or applications in machine learning
– New deep learning technology
– Other similar topics

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If you have any questions, please feel free to contact the editorial staff at the address below.

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